

## 100V - 100W DMOS AUDIO AMPLIFIER WITH MUTE/ST-BY

### 1 Features

- VERY HIGH OPERATING VOLTAGE RANGE ( $\pm 45V$ )
- MULTIPOWER BCD TECHNOLOGY
- DMOS POWER STAGE
- HIGH OUTPUT POWER (100W @ THD = 10%,  $R_L = 8\Omega$ ,  $V_S = \pm 40V$  (MUSIC POWER))
- MUTING/STAND-BY FUNCTIONS
- NO SWITCH ON/OFF NOISE
- VERY LOW DISTORTION
- VERY LOW NOISE
- SHORT CIRCUIT PROTECTED (WITH NO INPUT SIGNAL APPLIED)
- THERMAL SHUTDOWN
- CLIP DETECTOR
- MODULARITY (MORE DEVICES CAN BE EASILY CONNECTED IN PARALLEL TO DRIVE VERY LOW IMPEDANCES)

### 2 Description

The TDA7294S is a monolithic integrated circuit in Multiwatt15 package, intended for use as audio

Figure 1. Package

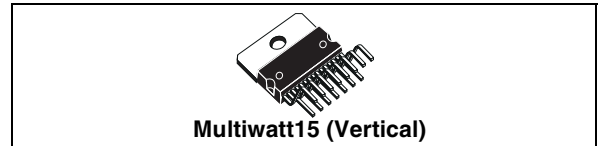


Table 1. Order Codes

Part Number	Package
TDA7294S	Multiwatt15 (Vertical)

class AB amplifier in Hi-Fi field applications (Home Stereo, self powered loudspeakers, Top class TV). Thanks to the wide voltage range and to the high out current capability it is able to supply the highest power into both 4 $\Omega$  and 8 $\Omega$  loads. The built in muting function with turn on delay simplifies the remote operation avoiding switching on-off noises.

Parallel mode is made possible by connecting more device through of pin11. High output power can be delivered to very low impedance loads, so optimizing the thermal dissipation of the system.

Figure 2. Typical Application and Test Circuit

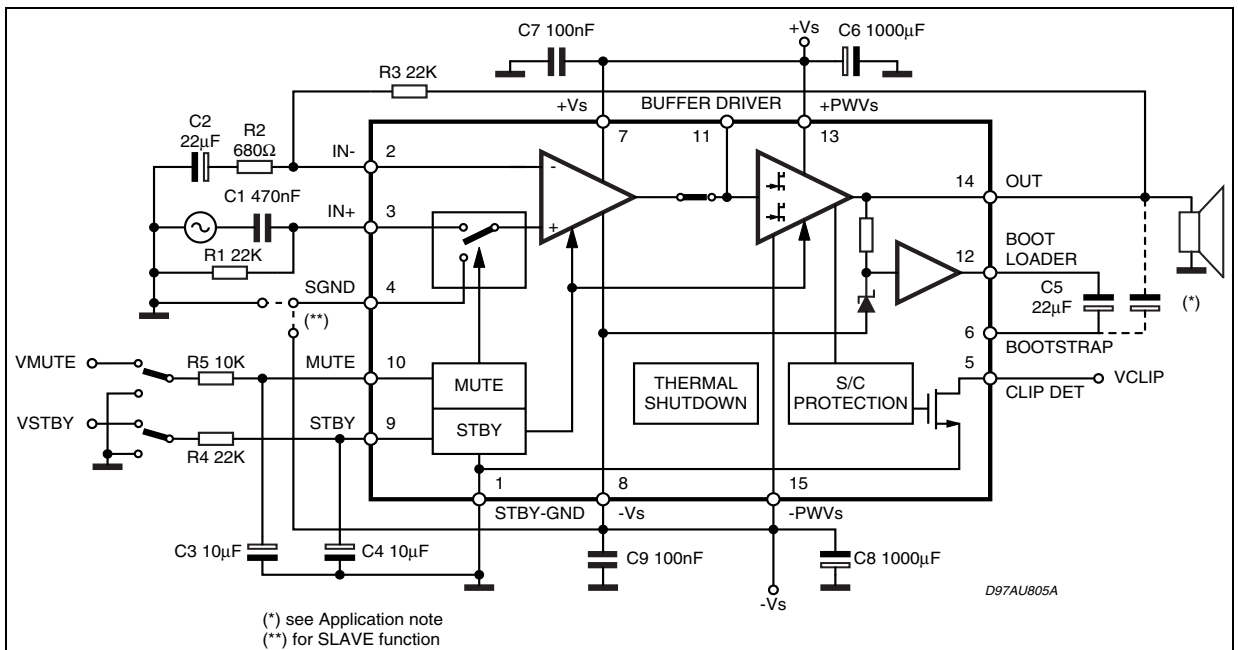


Figure 3. Pin Connection (Top view)

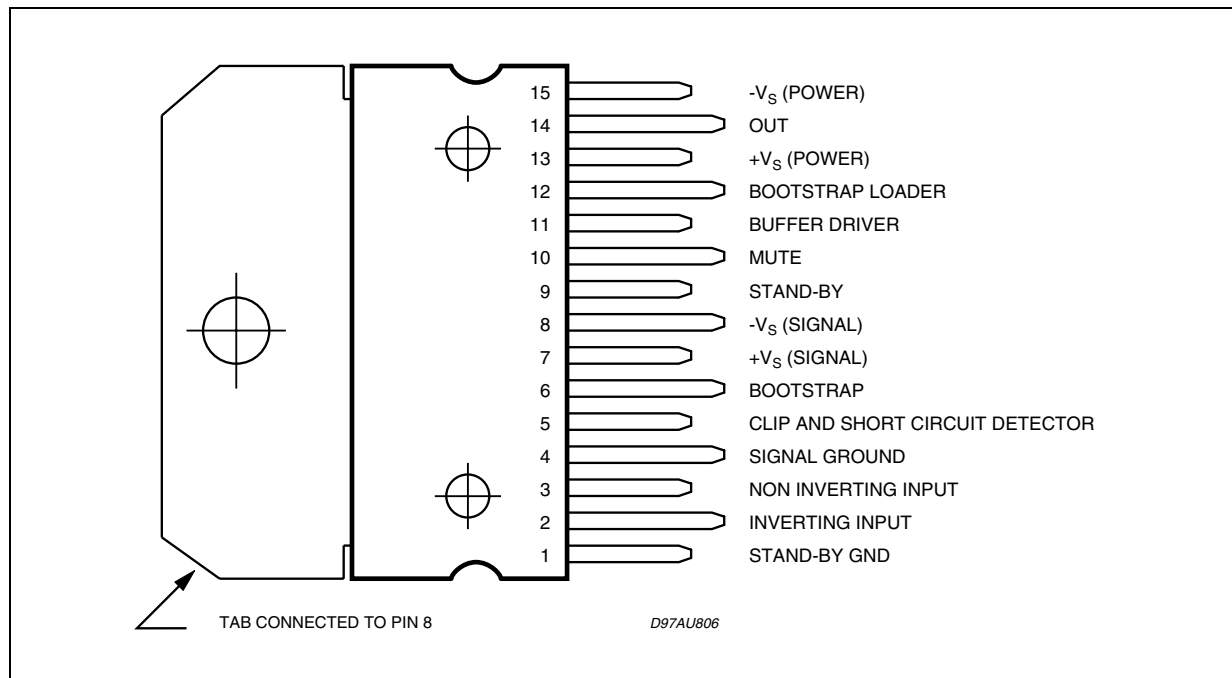


Table 2. Quick Reference Data

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
V <sub>S</sub>	Supply Voltage Operating		±12		±45	V
G <sub>LOOP</sub>	Closed Loop Gain		26		45	dB
P <sub>tot</sub>	Output Power	V <sub>S</sub> = ± 40V; R <sub>L</sub> = 8Ω; THD = 10%		100		W
		V <sub>S</sub> = ± 40V; R <sub>L</sub> = 8Ω; THD = 10%		100		W
SVR	Supply Voltage Rejection			75		dB

Table 3. Thermal Data

Symbol	Parameter	Typ	Max	Unit
R <sub>th j-case</sub>	Thermal Resistance Junction-case	1	1.5	°C/W

**Table 4. Absolute Maximum Ratings**

Symbol	Parameter	Value	Unit
V <sub>S</sub>	Supply Voltage (No Signal)	±50	V
V <sub>1</sub>	V <sub>STAND-BY</sub> GND Voltage Referred to -V <sub>S</sub> (pin 8)	90	V
V <sub>2</sub>	Input Voltage (inverting) Referred to -V <sub>S</sub>	90	V
V <sub>2</sub> - V <sub>3</sub>	Maximum Differential Inputs	±30	V
V <sub>3</sub>	Input Voltage (non inverting) Referred to -V <sub>S</sub>	90	V
V <sub>4</sub>	Signal GND Voltage Referred to -V <sub>S</sub>	90	V
V <sub>5</sub>	Clip Detector Voltage Referred to -V <sub>S</sub>	100	V
V <sub>6</sub>	Bootstrap Voltage Referred to -V <sub>S</sub>	100	V
V <sub>9</sub>	Stand-by Voltage Referred to -V <sub>S</sub>	100	V
V <sub>10</sub>	Mute Voltage Referred to -V <sub>S</sub>	100	V
V <sub>11</sub>	Buffer Voltage Referred to -V <sub>S</sub>	100	V
V <sub>12</sub>	Bootstrap Loader Voltage Referred to -V <sub>S</sub>	90	V
I <sub>O</sub>	Output Peak Current	10	A
P <sub>tot</sub>	Power Dissipation T <sub>case</sub> = 70°C	50	W
T <sub>op</sub>	Operating Ambient Temperature Range	0 to 70	°C
T <sub>stg</sub> , T <sub>j</sub>	Storage and Junction Temperature	150	°C

**Table 5. Electrical Characteristics**

(Refer to the Test Circuit V<sub>S</sub> = ±35V, R<sub>L</sub> = 8Ω, G<sub>V</sub> = 30dB; R<sub>g</sub> = 50Ω; T<sub>amb</sub> = 25°C, f = 1kHz; unless otherwise specified).

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
V <sub>S</sub>	Operating Supply Range		±12		±45	V
I <sub>q</sub>	Quiescent Current		20	30	65	mA
I <sub>b</sub>	Input Bias Current				500	nA
V <sub>OS</sub>	Input Offset Voltage				±10	mV
I <sub>OS</sub>	Input Offset Current				±100	nA
P <sub>O</sub>	RMS Continuous Output Power	d = 0.5%: V <sub>S</sub> = ± 35V, R <sub>L</sub> = 8Ω V <sub>S</sub> = ± 32V, R <sub>L</sub> = 6Ω V <sub>S</sub> = ± 28V, R <sub>L</sub> = 4Ω	60 60 60	70 70 70		W W W
	Music Power (RMS) (*) Δt = 1s	d = 0.5%: V <sub>S</sub> = ± 40V, R <sub>L</sub> = 8Ω V <sub>S</sub> = ± 35V, R <sub>L</sub> = 6Ω V <sub>S</sub> = ± 30V, R <sub>L</sub> = 4Ω (***)		100 100 100		W W W
d	Total Harmonic Distortion (**)	P <sub>O</sub> = 5W; f = 1kHz P <sub>O</sub> = 0.1 to 20W; f = 20Hz to 20kHz		0.005	0.1	% %
		V <sub>S</sub> = ± 28V, R <sub>L</sub> = 4Ω: P <sub>O</sub> = 5W; f = 1kHz P <sub>O</sub> = 0.1 to 20W; f = 20Hz to 20kHz		0.01	0.1	% %
I <sub>MAX</sub>	Overcurrent Protection Threshold	V <sub>S</sub> ≤ ± 40V	6.5			A
SR	Slew Rate		7	10		V/μs
G <sub>V</sub>	Open Loop Voltage Gain			80		dB
G <sub>V</sub>	Closed Loop Voltage Gain		26	30	45	dB

**Table 5. Electrical Characteristics** (continued)

(Refer to the Test Circuit  $V_S = \pm 35V$ ,  $R_L = 8\Omega$ ,  $G_V = 30dB$ ;  $R_g = 50\Omega$ ;  $T_{amb} = 25^\circ C$ ,  $f = 1kHz$ ; unless otherwise specified).

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
$e_N$	Total Input Noise	A = curve $f = 20Hz$ to $20kHz$		1		$\mu V$
				2	5	$\mu V$
$f_L, f_H$	Frequency Response (-3dB)	$P_O = 1W$	20Hz to 20kHz			
$R_i$	Input Resistance			100		$k\Omega$
SVR	Supply Voltage Rejection	$f = 100Hz$ ; $V_{ripple} = 0.5V_{rms}$	60	75		dB
$T_S$	Thermal Shutdown			150		$^\circ C$
<b>STAND-BY FUNCTION (Ref: <math>-V_S</math> or GND)</b>						
$V_{ST\ on}$	Stand-by on Threshold				1.5	V
$V_{ST\ off}$	Stand-by off Threshold		3.5			V
$ATT_{st-by}$	Stand-by Attenuation		70	90		dB
$I_{q\ st-by}$	Quiescent Current @ Stand-by			1	3	mA
<b>MUTE FUNCTION (Ref: <math>-V_S</math> or GND)</b>						
$V_{Mon}$	Mute on Threshold				1.5	V
$V_{Moff}$	Mute off Threshold		3.5			V
$ATT_{mute}$	Mute Attenuation		60	80		dB
<b>CLIP DETECTOR</b>						
Duty	Duty Cycle ( pin 5)	THD = 1%; $R_L = 10K\Omega$ to 5V		10		%
		THD = 10%; $R_L = 10K\Omega$ to 5V	30	40	50	%
$I_{CLEAK}$		$P_O = 50W$			3	$\mu A$

**Note (\*):**

MUSIC POWER CONCEPT

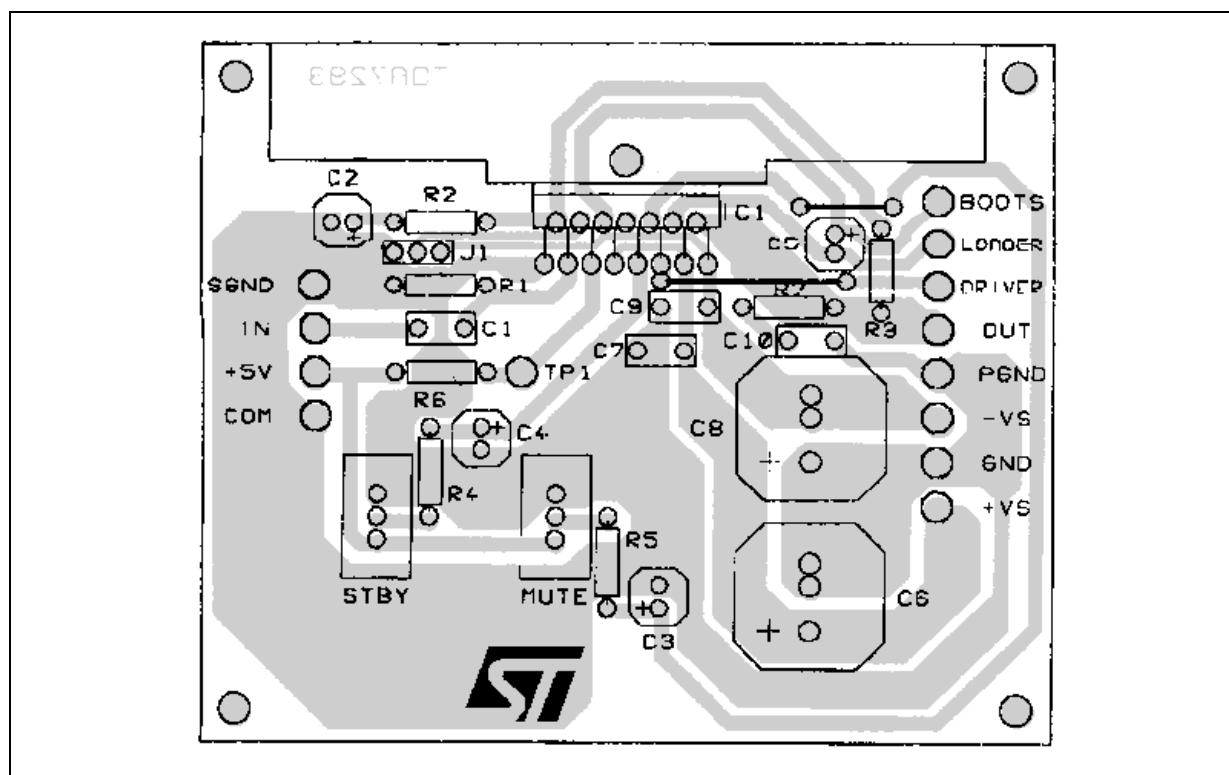
MUSIC POWER is the maximal power which the amplifier is capable of producing across the rated load resistance (regardless of non linearity) 1 sec after the application of a sinusoidal input signal of frequency 1KHz.

**Note (\*\*):** Tested with optimized Application Board (see fig. 3)

**Note (\*\*\*):** Limited by the max. allowable current.

**Note (\*\*\*\*):** For supply voltage  $\geq 35V$ , The device could be damaged in short circuit conditions when the input signal is applied

Figure 4. Typical Application P.C. Board and Component Layout (scale 1:1)



### 3 Application Suggestions (see Test and Application Circuits of the Fig. 2)

The recommended values of the external components are those shown on the application circuit of Figure 2. Different values can be used; the following table can help the designer.

**Table 6. Application Suggestions**

COMPONENTS	SUGGESTED VALUE	PURPOSE	LARGER THAN SUGGESTED	SMALLER THAN SUGGESTED
R1 (*)	22k	INPUT RESISTANCE	INCREASE INPUT IMPEDANCE	DECREASE INPUT IMPEDANCE
R2	680 $\Omega$	CLOSED LOOP GAIN SET TO 30dB (**)	DECREASE OF GAIN	INCREASE OF GAIN
R3 (*)	22k		INCREASE OF GAIN	DECREASE OF GAIN
R4	22k	ST-BY TIME CONSTANT	LARGER ST-BY ON/OFF TIME	SMALLER ST-BY ON/OFF TIME; POP NOISE
R5	10k	MUTE TIME CONSTANT	LARGER MUTE ON/OFF TIME	SMALLER MUTE ON/OFF TIME
C1	0.47 $\mu$ F	INPUT DC DECOUPLING		HIGHER LOW FREQUENCY CUTOFF
C2	22 $\mu$ F	FEEDBACK DC DECOUPLING		HIGHER LOW FREQUENCY CUTOFF
C3	10 $\mu$ F	MUTE TIME CONSTANT	LARGER MUTE ON/OFF TIME	SMALLER MUTE ON/OFF TIME

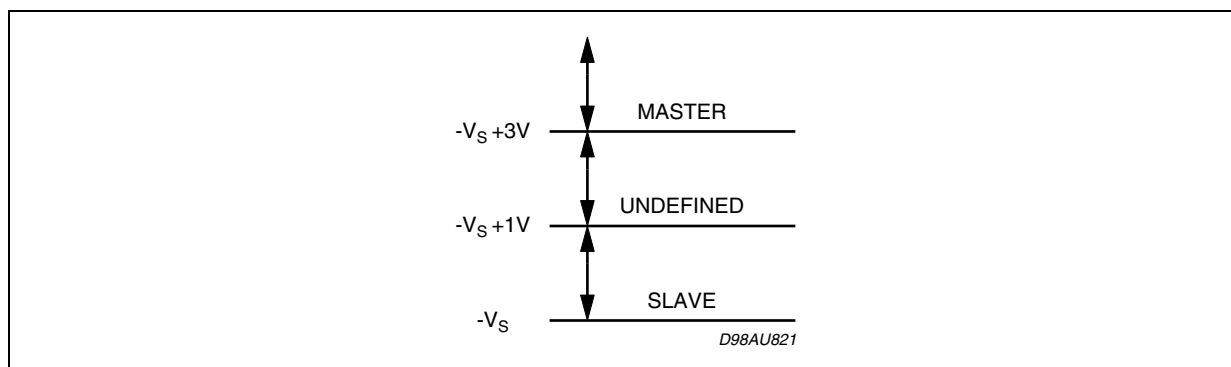
**Table 6. Application Suggestions** (continued)

COMPONENTS	SUGGESTED VALUE	PURPOSE	LARGER THAN SUGGESTED	SMALLER THAN SUGGESTED
C4	10 $\mu$ F	ST-BY TIME CONSTANT	LARGER ST-BY ON/OFF TIME	SMALLER ST-BY ON/OFF TIME; POP NOISE
C5	22 $\mu$ FXN (***)	BOOTSTRAPPING		SIGNAL DEGRADATION AT LOW FREQUENCY
C6, C8	1000 $\mu$ F	SUPPLY VOLTAGE BYPASS		
C7, C9	0.1 $\mu$ F	SUPPLY VOLTAGE BYPASS		DANGER OF OSCILLATION

(\*) R1 = R3 for pop optimization

(\*\*) Closed Loop Gain has to be  $\geq 26$ dB

(\*\*\*) Multiply this value for the number of modular part connected

**Figure 5. Slave function: pin 4 (Ref to pin 8 -V<sub>S</sub>)****Note:**

If in the application, the speakers are connected via long wires, it is a good rule to add between the output and GND, a Boucherot Cell, in order to avoid dangerous spurious oscillations when the speakers terminal are shorted. The suggested Boucherot Resistor is 3.9 $\Omega$ /2W and the capacitor is 1 $\mu$ F.

## 4 Introduction

In consumer electronics, an increasing demand has arisen for very high power monolithic audio amplifiers able to match, with a low cost, the performance obtained from the best discrete designs.

The task of realizing this linear integrated circuit in conventional bipolar technology is made extremely difficult by the occurrence of 2<sup>nd</sup> breakdown phenomenon. It limits the safe operating area (SOA) of the power devices, and, as a consequence, the maximum attainable output power, especially in presence of highly reactive loads. Moreover, full exploitation of the SOA translates into a substantial increase in circuit and layout complexity due to the need of sophisticated protection circuits.

To overcome these substantial drawbacks, the use of power MOS devices, which are immune from secondary breakdown is highly desirable. The device described has therefore been developed in a mixed bipolar-MOS high voltage technology called BCDII 100.

### 4.1 Output Stage

The main design task in developing a power operational amplifier, independently of the technology used, is that of realization of the output stage. The solution shown as a principle schematic by Fig.5 represents the DMOS unity - gain output buffer of the TDA7294S.

This large-signal, high-power buffer must be capable of handling extremely high current and voltage levels while maintaining acceptably low harmonic distortion and good behaviour over frequency response; moreover, an accurate control of quiescent current is required.

A local linearizing feedback, provided by differential amplifier A, is used to fulfill the above requirements, allowing a simple and effective quiescent current setting.

Proper biasing of the power output transistors alone is however not enough to guarantee the absence of crossover distortion.

While a linearization of the DC transfer characteristic of the stage is obtained, the dynamic behaviour of the system must be taken into account. A significant aid in keeping the distortion contributed by the final stage as low as possible is provided by the compensation scheme, which exploits the direct connection of the Miller capacitor at the amplifier's output to introduce a local AC feedback path enclosing the output stage itself.

## 4.2 Protections

In designing a power IC, particular attention must be reserved to the circuits devoted to protection of the device from short circuit or overload conditions. Due to the absence of the 2<sup>nd</sup> breakdown phenomenon, the SOA of the power DMOS transistors is delimited only by a maximum dissipation curve dependent on the duration of the applied stimulus.

In order to fully exploit the capabilities of the power transistors, the protection scheme implemented in this device combines a conventional SOA protection circuit with a novel local temperature sensing technique which "dynamically" controls the maximum dissipation.

**Figure 6. Principle Schematic of a DMOS unity-gain buffer.**

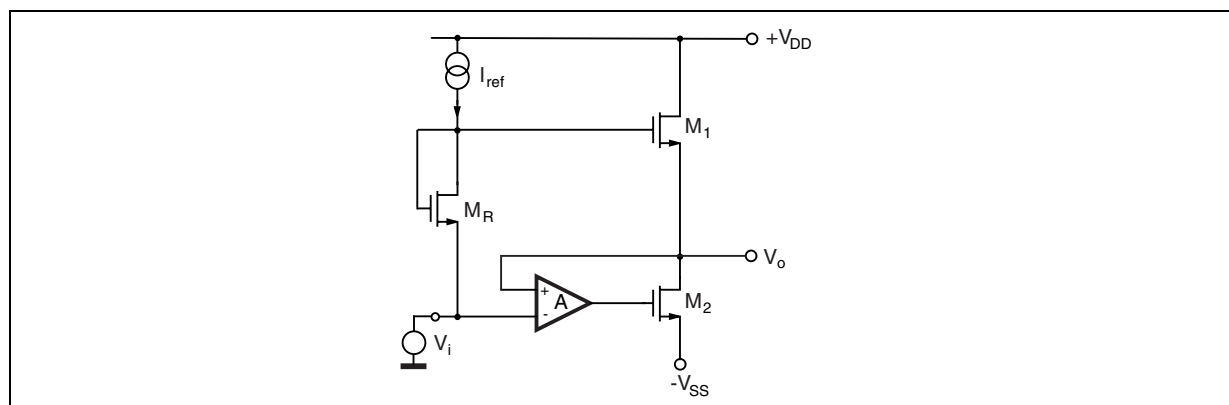


Figure 7. Turn ON/OFF Suggested Sequence

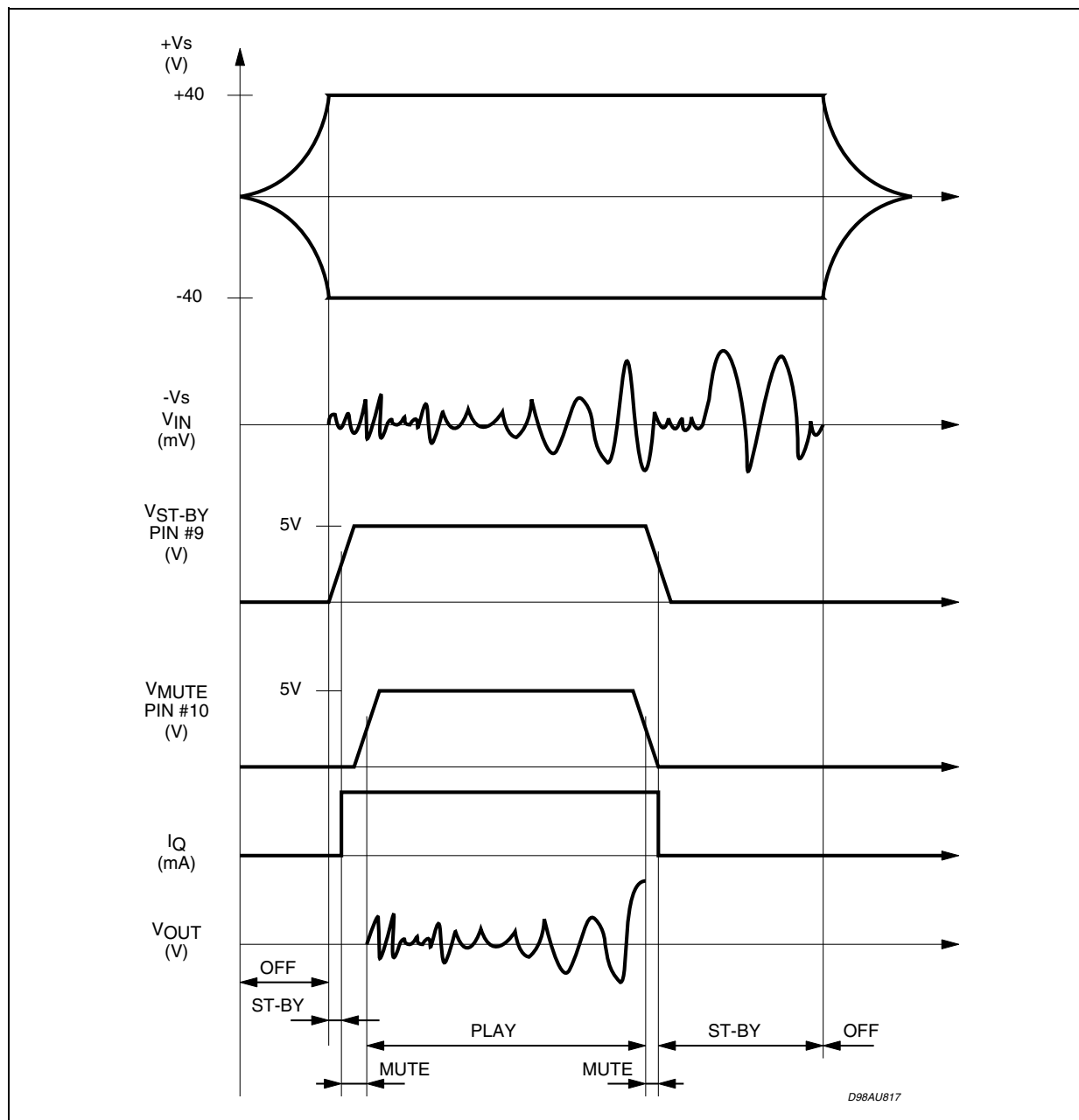
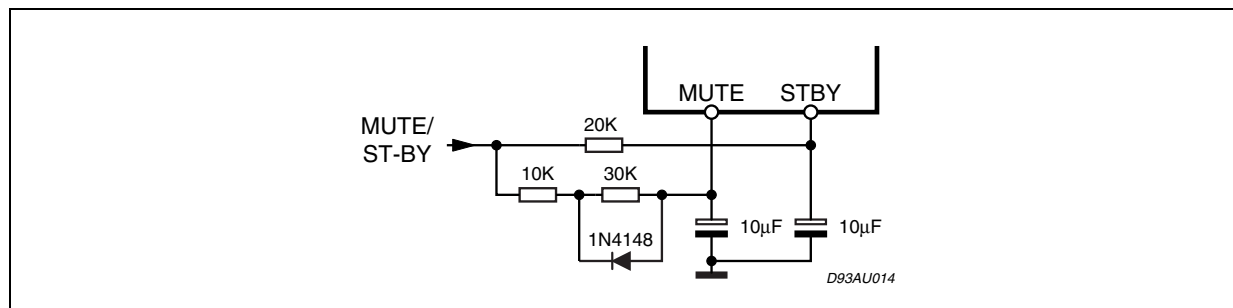


Figure 8. Single Signal ST-BY/MUTE Control Circuit





In addition to the overload protection described above, the device features a thermal shutdown circuit which initially puts the device into a muting state (@  $T_j = 150^\circ\text{C}$ ) and then into stand-by (@  $T_j = 160^\circ\text{C}$ ). Full protection against electrostatic discharges on every pin is included.

### 4.3 Other Features

The device is provided with both stand-by and mute functions, independently driven by two CMOS logic compatible input pins.

The circuits dedicated to the switching on and off of the amplifier have been carefully optimized to avoid any kind of uncontrolled audible transient at the output.

The sequence that we recommend during the ON/OFF transients is shown by Figure 7.

The application of figure 5 shows the possibility of using only one command for both st-by and mute functions. On both the pins, the maximum applicable range corresponds to the operating supply voltage.

## 5 Application Information

### 5.1 HIGH-EFFICIENCY

Constraints of implementing high power solutions are the power dissipation and the size of the power supply. These are both due to the low efficiency of conventional AB class amplifier approaches.

Here below (figure 9) is described a circuit proposal for a high efficiency amplifier which can be adopted for both HI-FI and CAR-RADIO applications.

The TDA7294S is a monolithic MOS power amplifier which can be operated at 90V supply voltage (100V with no signal applied) while delivering output currents up to  $\pm 6.5$  A.

This allows the use of this device as a very high power amplifier (up to 100W as peak power with T.H.D.=10 % and  $R_L = 4$  Ohm); the only drawback is the power dissipation, hardly manageable in the above power range.

The typical junction-to-case thermal resistance of the TDA7294S is  $1^\circ\text{C/W}$  (max=  $1.5^\circ\text{C/W}$ ). To avoid that, in worst case conditions, the chip temperature exceeds  $150^\circ\text{C}$ , the thermal resistance of the heat-sink must be  $0.038^\circ\text{C/W}$  (@ max ambient temperature of  $50^\circ\text{C}$ ).

As the above value is practically unreachable; a high efficiency system is needed in those cases where the continuous RMS output power is higher than 50-60 W.

The TDA7294S was designed to work also in higher efficiency way.

For this reason there are four power supply pins: two intended for the signal part and two for the power part.

T1 and T2 are two power transistors that only operate when the output power reaches a certain threshold (e.g. 20 W). If the output power increases, these transistors are switched on during the portion of the signal where more output voltage swing is needed, thus "bootstrapping" the power supply pins (#13 and #15).

The current generators formed by T4, T7, zener diodes Z1, Z2 and resistors R7,R8 define the minimum drop across the power MOS transistors of the TDA7294S. L1, L2, L3 and the snubbers C9, R1 and C10, R2 stabilize the loops formed by the "bootstrap" circuits and the output stage of the TDA7294S.

By considering again a maximum average output power (music signal) of 20W, in case of the high efficiency application, the thermal resistance value needed from the heatsink is  $2.2^\circ\text{C/W}$  ( $V_s = \pm 45\text{V}$  and  $R_L = 8\text{Ohm}$ ).

All components (TDA7294S and power transistors T1 and T2) can be placed on a  $1.5^\circ\text{C/W}$  heatsink, with the power darlington electrically insulated from the heatsink.

Since the total power dissipation is less than that of a usual class AB amplifier, additional cost savings can be obtained while optimizing the power supply, even with a high heatsink .

## 5.2 BRIDGE APPLICATION

Another application suggestion is the BRIDGE configuration, where two TDA7294S are used. In this application, the value of the load must not be lower than 8Ohm for dissipation and current capability reasons. A suitable field of application includes HI-FI/TV subwoofers realizations.

The main advantages offered by this solution are:

- High power performances with limited supply voltage level.
- Considerably high output power even with high load values (i.e. 16 Ohm).

With  $R_l = 8 \text{ Ohm}$ ,  $V_s = \pm 25\text{V}$  the maximum output power obtainable is 150W, while with  $R_l = 16 \text{ Ohm}$ ,  $V_s = \pm 40\text{V}$  the maximum  $P_{out}$  is 200W (Music Power).

## 6 APPLICATION NOTE: (ref. fig. 10)

### 6.1 Modular Application (more Devices in Parallel)

The use of the modular application lets very high power be delivered to very low impedance loads. The modular application implies one device to act as a master and the others as slaves.

The slave power stages are driven by the master device and work in parallel all together, while the input and the gain stages of the slave device are disabled, the figure below shows the connections required to configure two devices to work together.

- The master chip connections are the same as the normal single ones.
- The outputs can be connected together **without the need of any ballast resistance**.
- The slave SGND pin must be tied to the negative supply.
- The slave ST-BY pin must be connected to ST-BY pin.
- The bootstrap lines must be connected together and the bootstrap capacitor must be increased: for N devices the bootstrap capacitor must be  $22\mu\text{F}$  times N.
- The slave Mute and IN-pins must be grounded.

### 6.2 THE BOOTSTRAP CAPACITOR

For compatibility purpose with the previous devices of the family, the bootstrap capacitor can be connected both between the bootstrap pin (6) and the output pin (14) or between the bootstrap pin (6) and the bootstrap loader pin (12).

When the bootcap is connected between pin 6 and 14, the maximum supply voltage in presence of output signal is limited to 80V, due the bootstrap capacitor overvoltage.

When the bootcap is connected between pins 6 and 12 the maximum supply voltage extend to the full voltage that the technology can stand: 100V. This is accomplished by the clamp introduced at the bootstrap loader pin (12): this pin follows the output voltage up to 100V and remains clamped at 100V. This feature lets the output voltage swing up to a gate-source voltage from the positive supply ( $V_s - 3$  to 6V)

Figure 9. High Efficiency Application Circuit

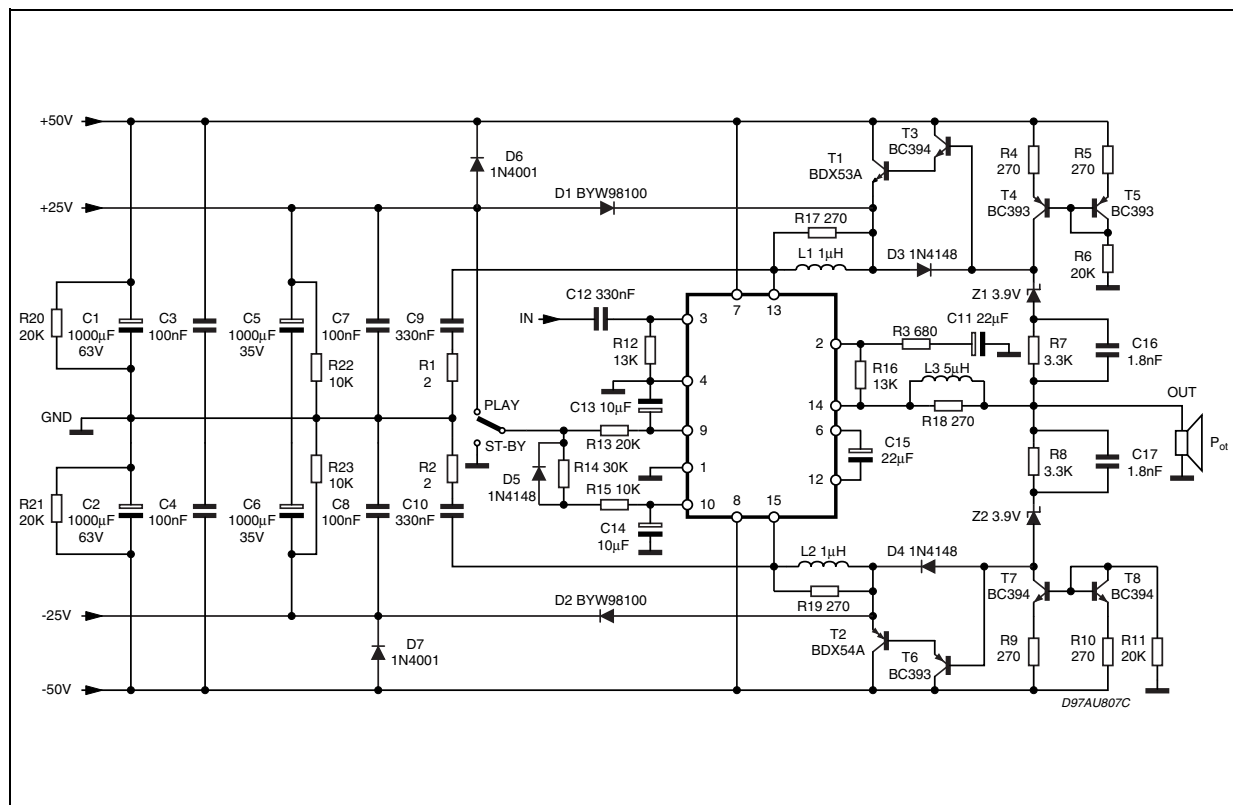


Figure 10. PCB and Component Layout of the fig. 9

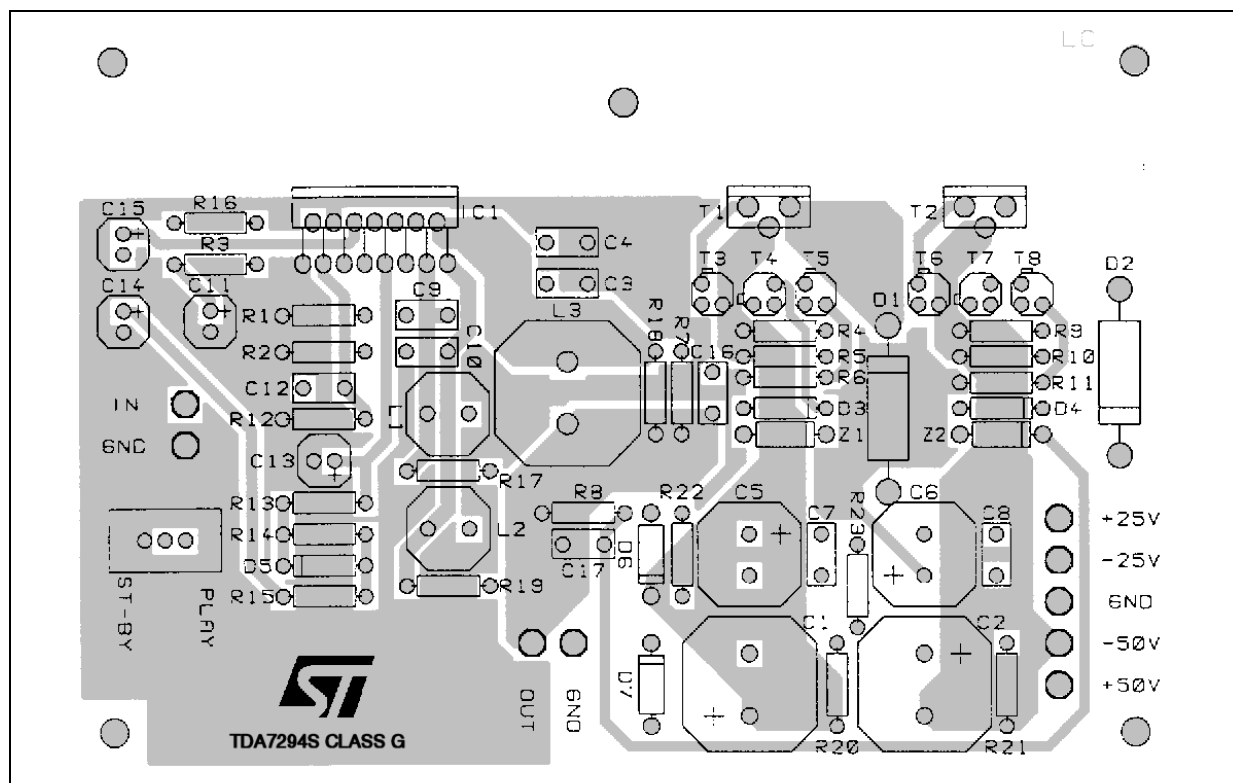


Figure 11. PCB and Component Layout of the fig. 9

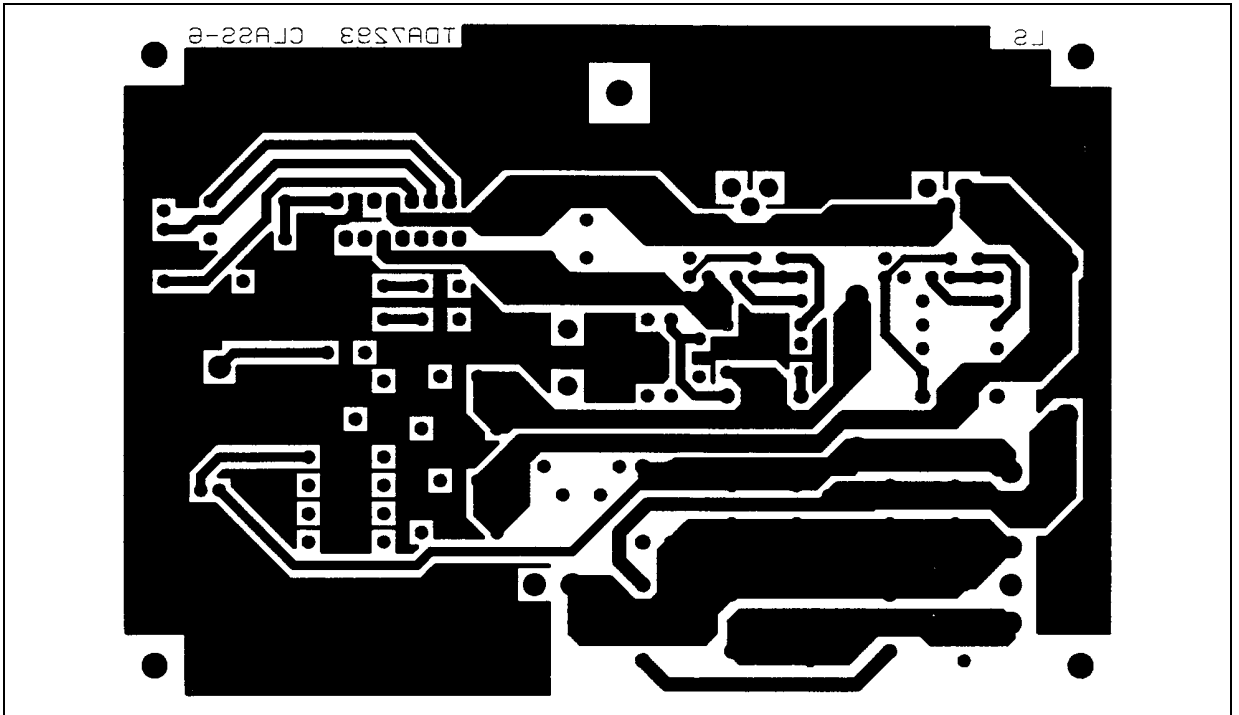


Figure 12. Modular Application Circuit

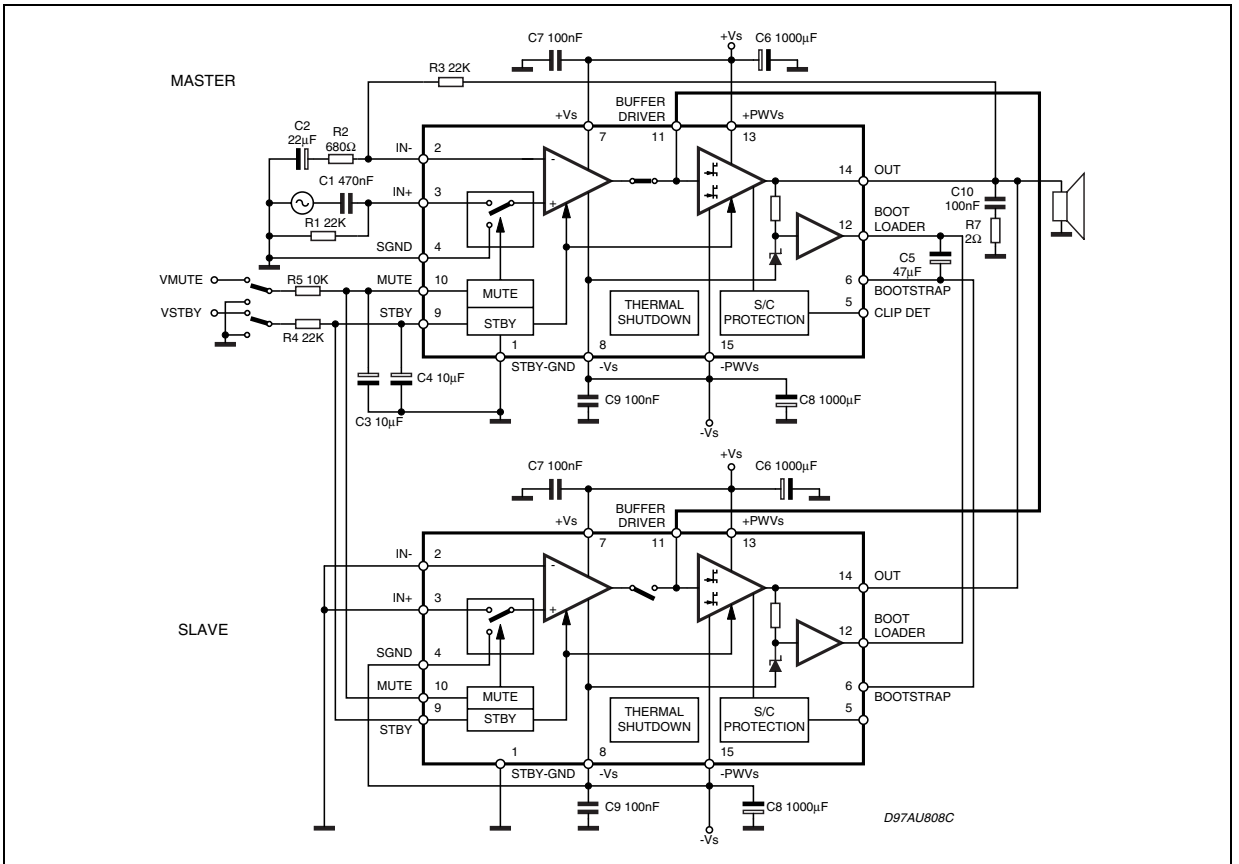


Figure 13. Modular Application P.C. Board and Component Layout (Component SIDE)

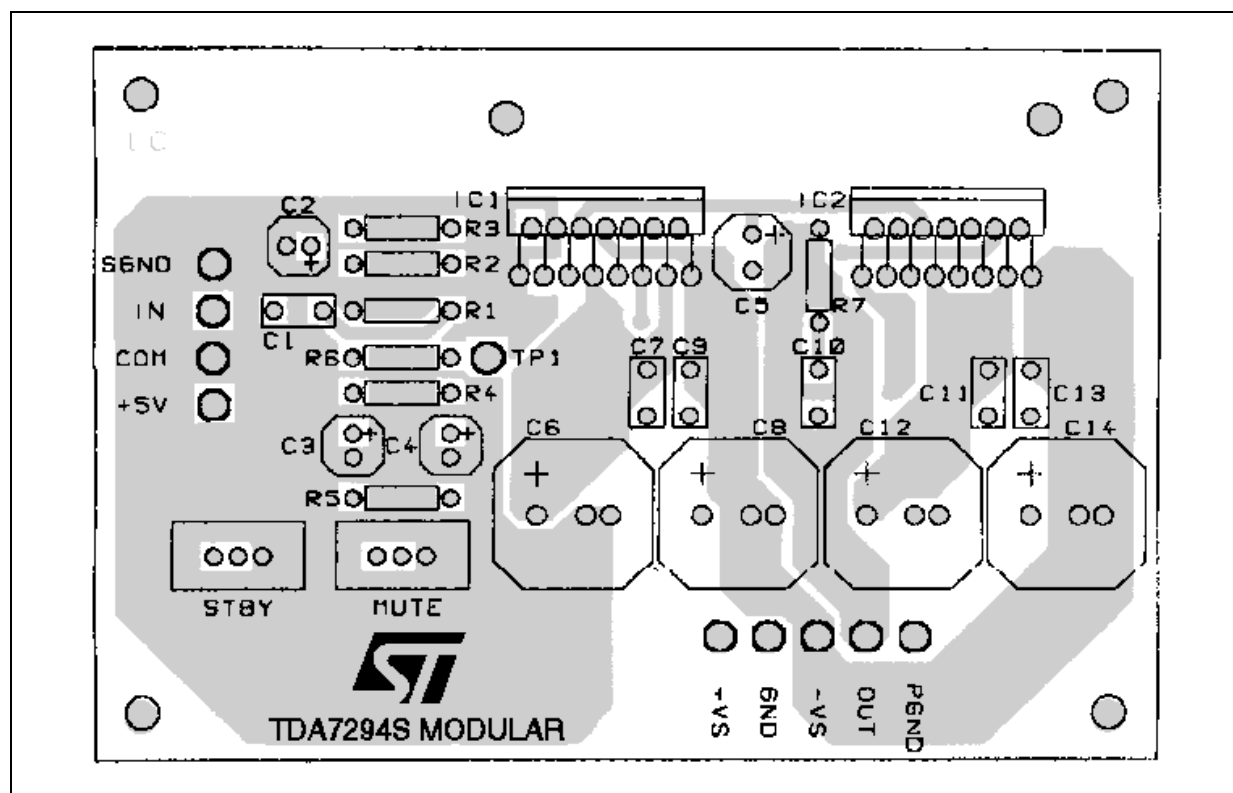
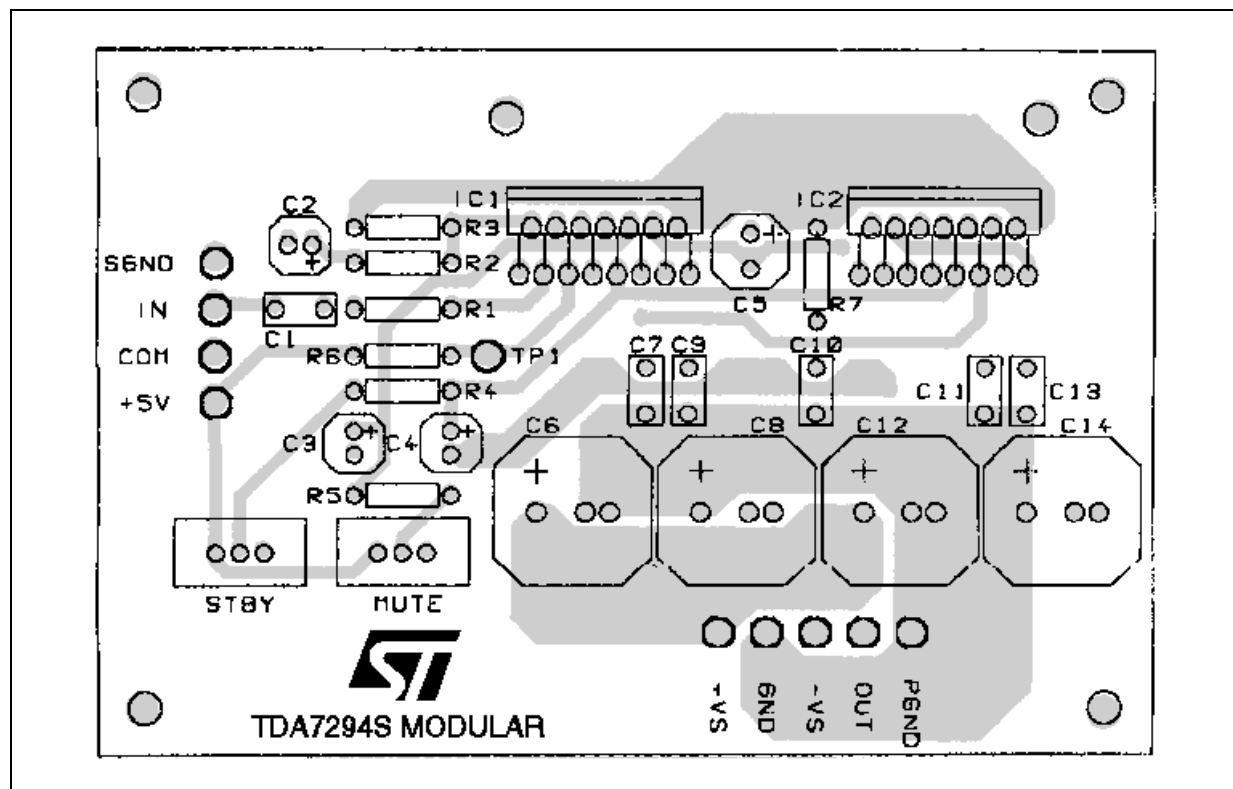


Figure 14. Modular Application P.C. Board and Component Layout (Solder SIDE)

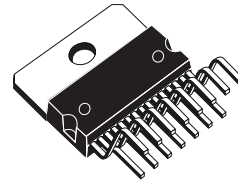


## 7 Package Information

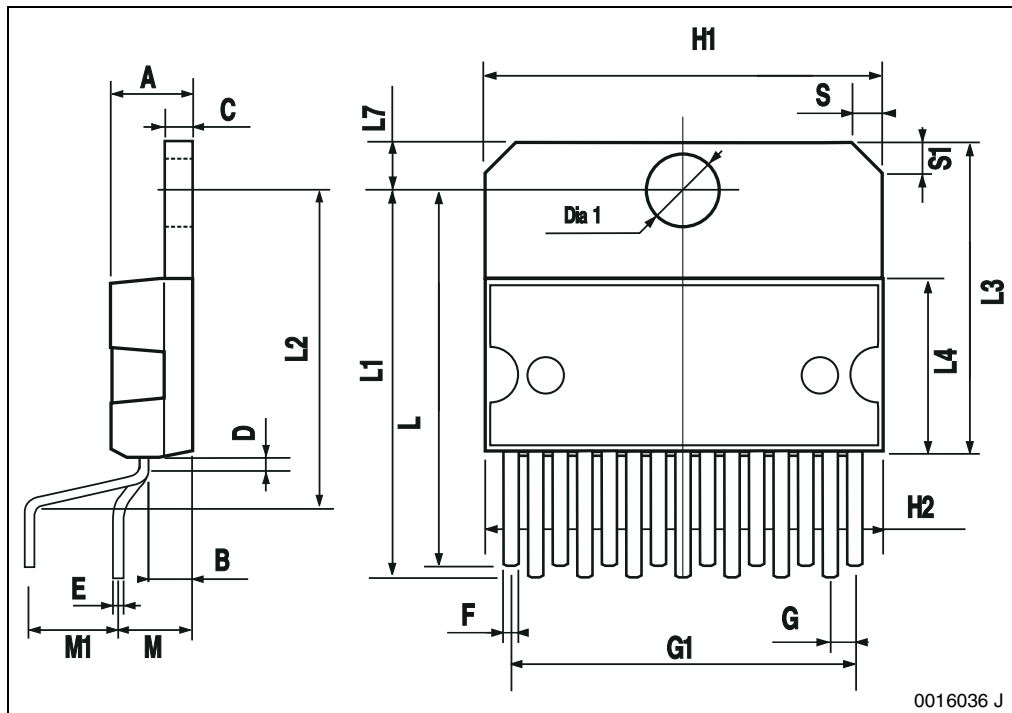
Figure 15. Multiwatt15 (Vertical) Mechanical Data & Package Dimensions

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A5						0.197
B			2.65			0.104
C			1.6			0.063
D		1			0.039	
E	0.49		0.55	0.019		0.022
F	0.66		0.75	0.026		0.030
G	1.02	1.27	1.52	0.040	0.050	0.060
G1	17.53	17.78	18.03	0.690	0.700	0.710
H1	19.6			0.772		
H2			20.2			0.795
L	21.9	22.2	22.5	0.862	0.874	0.886
L1	21.7	22.1	22.5	0.854	0.87	0.886
L2	17.65		18.1	0.695		0.713
L3	17.25	17.5	17.75	0.679	0.689	0.699
L4	10.3	10.7	10.9	0.406	0.421	0.429
L7	2.65		2.9	0.104		0.114
M	4.25	4.55	4.85	0.167	0.179	0.191
M1	4.73	5.08	5.43	0.186	0.200	0.214
S	1.9		2.6	0.075		0.102
S1	1.9		2.6	0.075		0.102
Dia1	3.65		3.85	0.144		0.152

### OUTLINE AND MECHANICAL DATA



### Multiwatt15 (Vertical)



0016036 J

## 8 Revision History

**Table 7. Revision History**

Date	Revision	Description of Changes
January 2003	1	First Issue in EDOCS (migrated from ST-Press DMS).
February 2005	2	Added "Clip Detector Electrical Characteristics" in the Table 5 (page 6).

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